

LTKAK3 Series



Description

The LTKAK3 series offers superior clamping characteristics over standard S.A.D. technologies by virtue of the Littelfuse Foldbak™ technology, which provides a clamping voltage lower than the avalanche voltage (but above the rated working voltage). Therefore, any voltage rise due to increased current conduction is contained to a minimum, providing the best possible protection level. This LTKAK3 series can be combined in series or parallel solutions to offer various clamping levels and surge withstand options.

The LTKAK3 SMT package provides a more compact PCB layout than typical through-hole TO-218 AKTVS components.

Agency Recognitions

AGENCY	AGENCY FILE NUMBER
	E128662

Maximum Ratings and Thermal Characteristics
(T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Junction Temperature	T _J	-55 to 125	°C
Storage Temperature	T _{STG}	-55 to 150	°C
Current Rating ¹	I _{PP}	3	kA
Typical Thermal Resistance Junction to Lead	R _{θJL}	10	°C/W
Typical Thermal Resistance Junction to Ambient	R _{θJA}	50	°C/W

Note:
1. Rated min I_{pp} measured with 8/20μs pulse.

Features

- Compact design having the Hi Power TVS in surface mount package
- Patent granted package design
- Foldbak™ Technology for superior clamping factor
- Tube or tape and reel pack options available
- Ideal for automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality as compared to axial leaded packages
- Meet MSL level1, per J-STD-020, LF maximum peak of 260°C
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- UL Recognized compound meeting flammability rating V-0
- Meets MSL level 1, per J-STD-020, lead frame maximum peak of 260°C

Electrical Characteristics (T_A=25°C unless otherwise noted)

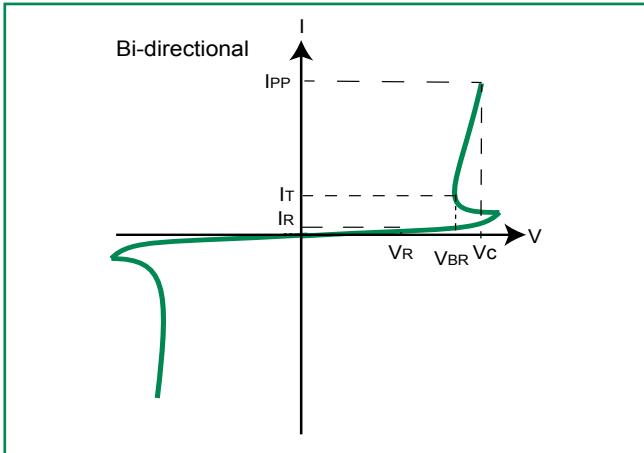
Part Numbers	Standoff Voltage (V _{SO}) Volts	Max. Reverse Leakage (I _R) @ V _{SO} μA	Reverse Breakdown Voltage (V _{BR}) @ I _T		Test Current I _T (mA)	Max. Clamping Voltage V _{CL} @ I _{pp} Volts	Max. Temp Coefficient OF V _{BR} (%/°C)	Max. Capacitance 0V bias 10kHz (nF)
			Min Volts	Max Volts				
LTKAK3-066C	66	10	72	80	10	120	0.1	6

Note: Using 8/20μs wave shaped defined in IEC 61000-4-5.

Surge Ratings

Part Numbers	Max. Peak Pulse Current (I _{pp})		
	(8/20μs) (A)	(10/350μs) (A)	(10/1000μs) (A)
	min	min	min
LTKAK3-066C	3,000	800	500

I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation –

Max power dissipation

V_R Stand-off Voltage –

Maximum voltage that can be applied to the TVS without operation

V_{BR} Breakdown Voltage –

Maximum voltage that flows through the TVS at a specified test current (I_T)

V_c Clamping Voltage –

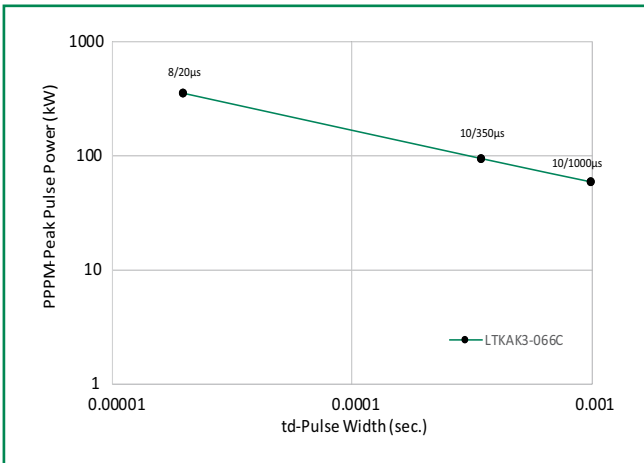
Peak voltage measured across the TVS at a specified I_{PPM} (peak impulse current)

I_R Reverse Leakage Current –

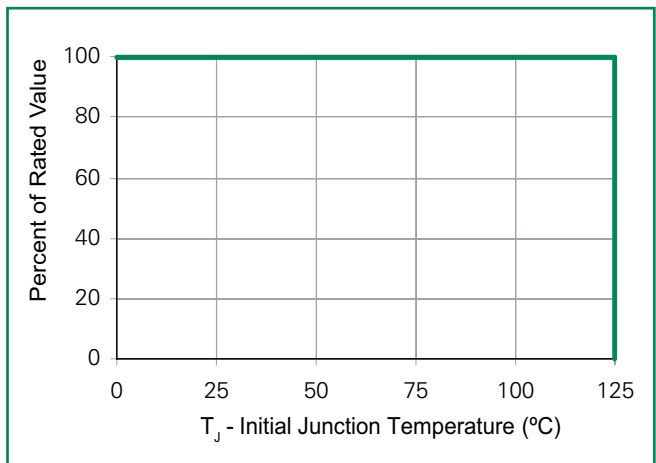
Current measured at V_R

Ratings and Characteristic Curves (T_A = 25°C unless otherwise noted)

Typical Peak Pulse Power Rating Curve

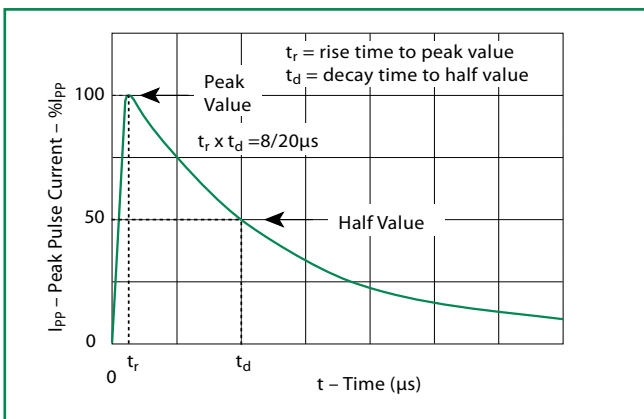


Peak Power Derating



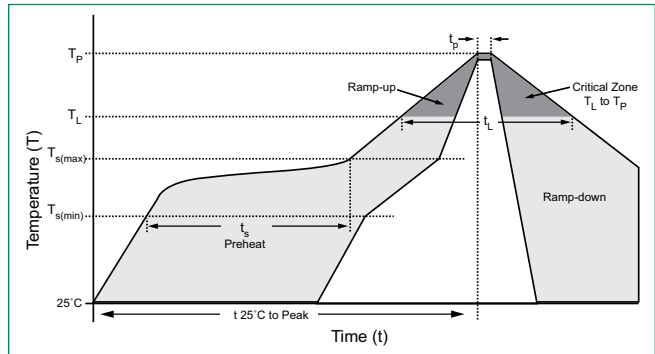
Please contact Littelfuse for reliability or FIT/MTBF data, the performance is subject to vary and depends on the end customers' application condition.

Pulse Waveform



Soldering Parameters

Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_A) to peak)		3°C/second max
$T_{s(max)}$ to T_A - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_A) (Liquidus)	217°C
	- Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Flow/Wave Soldering (Solder Dipping)

Peak Temperature :	265°C
Dipping Time :	10 seconds
Soldering :	1 time

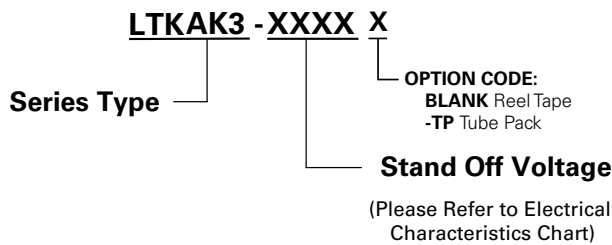
Physical Specifications

Weight	Contact manufacturer
Case	Compound encapsulated
Terminal	Tin plated lead, solderable per MIL-STD-202 Method 208

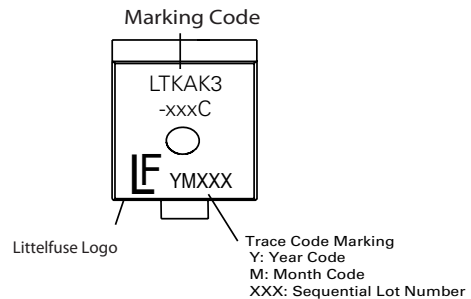
Environmental Specifications

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
MSL	JESDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-B106
Temperature cycling	JESD22-A104

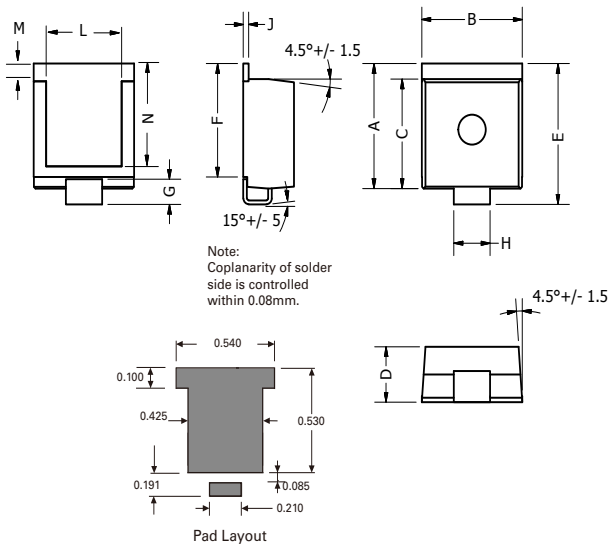
Part Numbering System



Part Marking System



Dimensions — SMT0-218

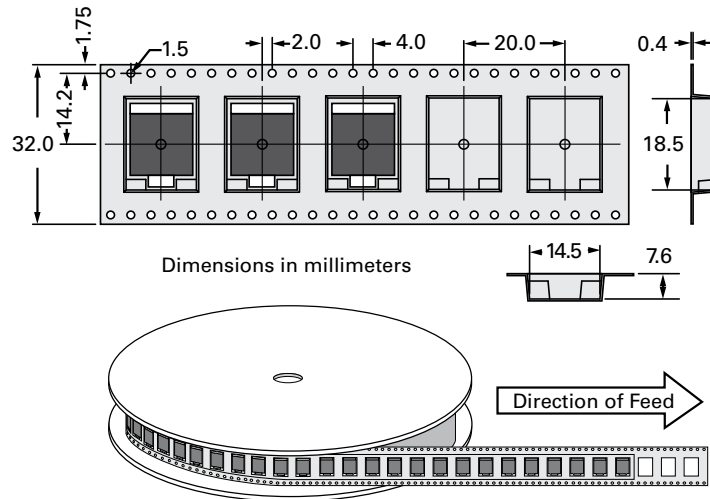


Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.621	0.655	15.78	16.63
B	0.529	0.594	13.43	15.09
C	0.544	0.561	13.83	14.24
D	0.273	0.285	6.94	7.24
E	0.702	0.737	17.82	18.72
F	0.567	0.587	14.40	14.90
G	0.087	0.126	2.20	3.20
H	0.193	0.222	4.89	5.65
J	0.028	0.033	0.72	0.85
L	0.400	0.440	10.17	11.17
M	0.073	0.112	1.85	2.85
N	0.510	0.533	12.95	13.55

Packaging

Part Number	Weight	Packing Mode	Base Quantity
LTKAK3-xxxC	4.215g	Tape & Reel – 32mm/13" tape	400
LTKAK3-xxxC-TP	4.215g	Tube Pack	100(25/Tube)

Tape and Reel Specification



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